

Amendments to the Specification

Please amend the Abstract as follows

The invention relates to a camera module. Consistent with an example embodiment there is an optical element that comprises at least one plate of transparent material of which, two sides are covered with a radiation-opaque layer having an aperture. The aperture in the radiation-opaque layer close to the sensor has a smaller surface than the aperture in the layer located remote from the sensor, and in which the primary and secondary areas are defined respectively by portions of the at least one plate sandwiched between the opaque layers and the apertures therein. Such a module is particularly well-suited to wafer-scale manufacturing.

~~———The invention relates to a camera module (10) which comprises a semiconductor housing (1) that contains a solid-state image sensor (2) with a radiation sensitive surface area (3), and an optical element (4) located above the solid-state sensor (2) and which forms a shield against laterally-scattered radiation, comprising a disk-shaped body with a primary radiation-opaque area and a secondary radiation-transparent area located within the primary area, of which a surface close to the sensor (2) is smaller than a surface more remote from the sensor (2).~~

~~———According to the invention the optical element (4) comprises at least one plate (40) of transparent material of which two sides are covered with a radiation-opaque layer (41,42) which is provided with an aperture, in which the aperture in the layer (41) close to the sensor (2) has a smaller surface than the aperture in the layer (42) located remote from the sensor (2), and in which the primary and secondary areas are defined respectively by portions of the at least one plate (40) sandwiched between the opaque layers (41,42) and the apertures therein. Such a module (10) is particularly well-suited to wafer-scale manufacturing. The invention also comprises a method for manufacturing such a module (10).~~

~~Fig. 1~~